



Mohamed Elattar (Autor)

# High-Power GaAs-Based Diode Lasers with Novel Lateral Designs for Enhanced Brightness, Threshold and Efficiency

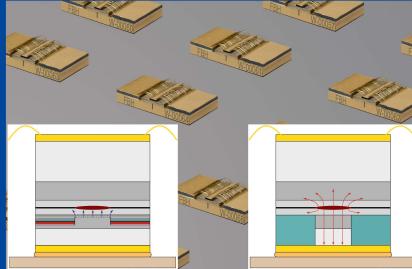


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Ferdinand-Braun-Institut,  
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für Hochfrequenztechnik

High-Power GaAs-Based Diode Lasers  
with Novel Lateral Designs for Enhanced  
Brightness, Threshold and Efficiency



Innovationen mit Mikrowellen & Licht

Mohamed Elattar

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